L	Hits	Search Text	DB	Time stamp
Number -	164	(710/317).CCLS.	USPAT;	2004/01/09
_	18	((710/317).CCLS.) and analog and digital	US-PGPUB USPAT;	12:03 2003/12/19
_	10	((/10/31/).cch3.) and analog and digital	US-PGPUB	14:17
_	37232	microcontroller	USPAT; US-PGPUB;	2003/12/19 13:51
			EPO; JPO; DERWENT;	13.31
	14360	microcontroller and analog and digital	IBM_TDB USPAT;	2003/12/19
	14300	microcontroller and analog and digital	US-PGPUB;	13:51
			EPO; JPO; DERWENT;	
			IBM_TDB	
-	2326	(microcontroller and analog and digital) and (wirebond or "wire bond" or pad)	USPAT; US-PGPUB;	2003/12/19
		and (wifebond of wife bond of pad)	EPO; JPO;	
			DERWENT; IBM TDB	
-	1714	((microcontroller and analog and digital)	USPĀT;	2003/12/19
		and (wirebond or "wire bond" or pad)) and processor	US-PGPUB; EPO; JPO;	13:52
		P2000001	DERWENT;	
_	1459	(((microcontroller and analog and	IBM_TDB USPAT;	2003/12/19
	1.00	digital) and (wirebond or "wire bond" or	US-PGPUB;	13:55
		pad)) and processor) and (crossbar or switch\$5)	EPO; JPO; DERWENT;	
			IBM_TDB	
-	1458	(((microcontroller and analog and digital) and (wirebond or "wire bond" or	USPAT; US-PGPUB	2003/12/19
		pad)) and processor) and (crossbar or		
_	37232	switch\$5) microcontroller	USPAT;	2003/12/19
			US-PGPUB;	14:11
			EPO; JPO; DERWENT;	
	21.6225		IBM_TDB	2002/12/10
-	316838	analog same digital	USPAT; US-PGPUB;	2003/12/19 14:11
			EPO; JPO;	
			DERWENT; IBM_TDB	
_	13231	microcontroller and (analog same digital)	USPAT; US-PGPUB;	2003/12/19
			EPO; JPO;	17.16
			DERWENT; IBM TDB	
_	0	((710/317).CCLS.) and wirebond	USPĀT;	2003/12/19
			US-PGPUB; EPO; JPO;	14:12
			DERWENT;	
_	8	(microcontroller and (analog same	IBM_TDB USPAT;	2003/12/19
		digital)) and wirebond	US-PGPUB;	14:12
			EPO; JPO; DERWENT;	
			IBM_TDB	0000/10/10
-	62	(microcontroller and (analog same digital)) and (wirebond or "wire bond")	USPAT; US-PGPUB;	2003/12/19 14:13
		argroup, and threshold or three sould	EPO; JPO;	
			DERWENT; IBM TDB	
-	55		USPĀT;	2003/12/19
		digital)) and (wirebond or "wire bond")) and (processor or microprocessor or cpu)	US-PGPUB; EPO; JPO;	14:14
		The transfer of mistopiosist of opay	DERWENT;	
<u> </u>	L		IBM_TDB	

	48	(((microcontroller and (analog same	USPAT;	2003/12/19
		digital)) and (wirebond or "wire bond"))	US-PGPUB;	14:16
		and (processor or microprocessor or cpu))	EPO; JPO;	
		and (switch\$4 or crossbar or "cross bar")	DERWENT;	
1			IBM_TDB	
_	0	((((microcontroller and (analog same	USPAT;	2003/12/19
		digital)) and (wirebond or "wire bond"))	US-PGPUB;	14:16
		and (processor or microprocessor or cpu))	EPO; JPO;	
		and (switch\$4 or crossbar or "cross	DERWENT;	
		bar")) not microcontroller	IBM TDB	
_	316838	analog same digital	USPAT;	2003/12/19
	310030	didialog band digital	US-PGPUB;	14:17
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
	803	(analog same digital) and (wirebond or	USPAT;	2003/12/19
-	003	"wire bond")	US-PGPUB;	14:17
		wife bond /	EPO; JPO;	14.1/
			DERWENT;	
			IBM TDB	
	400			2003/12/10
-	493	((analog same digital) and (wirebond or	USPAT;	2003/12/19
		"wire bond")) and (switch\$4 or crossbar	US-PGPUB;	14:18
		or "cross bar")	EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	301	(((analog same digital) and (wirebond or	USPAT;	2003/12/19
		"wire bond")) and (switch\$4 or crossbar	US-PGPUB;	17:05
		or "cross bar")) and (processor or	EPO; JPO;	
		microprocessor or cpu)	DERWENT;	
1			IBM_TDB	1
_	2	(("6144327") or ("5202687")).PN.	USPAT;	2003/12/19
			US-PGPUB	17:06
-	1	("6192431").PN.	USPAT;	2003/12/22
	_	1	US-PGPUB	13:19
-	0	6192431.URPN.	USPAT	2003/12/22
	1			13:15
_	l 0	6192431.URPN.	USPAT	2003/12/22
		V23B 1V21V1		13:15
_	6	("5701517" "5715197" "5737764"	USPAT	2003/12/22
		"5748982" "5822610" "5835965").PN.	"""	13:15
İ_	1649	(257/666).CCLS.	USPAT;	2003/12/22
	1049	(237/000).CCL3.	US-PGPUB	13:19
_	1335	((257/666).CCLS.) and (wirebond or "wire	USPAT;	2003/12/22
1	1333	((257/666).CCLS.) and (wirebond of wire bond" or pad)	US-PGPUB	14:01
1_	87	(((257/666).CCLS.) and (wirebond or "wire	USPAT;	2003/12/22
-	"		US-PGPUB	13:21
	0.1	bond" or pad)) and (processor or cpu)		2003/12/22
_	81	((((257/666).CCLS.) and (wirebond or	USPAT;	
		"wire bond" or pad)) and (processor or	US-PGPUB	13:23
		cpu)) and (switch or select\$6 or		
		configura\$5)	11055	2002/12/22
-	64	((((257/666).CCLS.) and (wirebond or	USPAT;	2003/12/22
		"wire bond" or pad)) and (processor or	US-PGPUB	13:23
		cpu)) and (switch or select\$6 or		
		configurable or reconfigurable or		
		re-configurable)		0000 /50 /00
-	429	((257/666).CCLS.) and (wirebond or "wire	USPAT;	2003/12/22
		bond")	US-PGPUB	14:03
-	43	(((257/666).CCLS.) and (wirebond or "wire	USPAT;	2003/12/22
1		bond")) and (processor or cpu)	US-PGPUB	14:02
~	482	((257/666).CCLS.) and ((wirebond or "wire	USPAT;	2003/12/22
1		bond") next10 (processor or cpu))	US-PGPUB	14:03
-	422718	("wire bond" or wirebond) next10	USPAT;	2003/12/22
1		(processor or cpu)	US-PGPUB	14:04
~	482	(("wire bond" or wirebond) next10	USPAT;	2003/12/22
		(processor or cpu)) and ((257/666).CCLS.)	US-PGPUB	14:04
-	17	("wirebond pad" or "wire bond pad")	USPAT;	2003/12/22
		near10 (processor or cpu)	US-PGPUB	14:07
_	48	(wirebond or "wire bond") near10	USPAT;	2003/12/22
		(processor or cpu)	US-PGPUB	14:08
-	8	((wirebond or "wire bond") near10	USPAT;	2003/12/22
		(processor or cpu)) same (switch or	US-PGPUB	14:10
		configura \$6 or select \$6)		
L	L			L

-	1	("5563529").PN.	USPAT;	2003/12/22
	_		US-PGPUB	14:12
-	1	("6445242").PN.	USPAT;	2003/12/22
	1122	(057/676) 6615	US-PGPUB USPAT;	14:14 2003/12/22
-	1133	(257/676).CCLS.	US-PGPUB	14:14
	207	"wirebond pad"	USPAT;	2003/12/22
-	207	wilebond pad	US-PGPUB	14:15
_	1183	"wire bond pad"	USPAT;	2003/12/22
			US-PGPUB	14:15
-	1351	"wirebond pad" or "wire bond pad"	USPAT;	2003/12/22
		-	US-PGPUB	14:16
-	188	("wirebond pad" or "wire bond pad") and	USPAT;	2003/12/22
		processor	US-PGPUB	14:17
-	2443436	switch\$6 or select\$6 or reconfigurable or	USPAT;	2003/12/22
		re-configurable or configurable	US-PGPUB	14:18 2003/12/22
_	0	(("wirebond pad" or "wire bond pad") near10 (processor or cpu)) near10	USPAT; US-PGPUB	14:20
		(switch\$5 or select\$5 or configurable or	US-PGPUB	14.20
		reconfigurable or re-configurable)		
_	0	(("wirebond pad" or "wire bond pad")	USPAT;	2003/12/22
		near10 (processor or cpu)) same (switch\$5	US-PGPUB	14:20
		or select\$5 or configurable or		
		reconfigurable or re-configurable)		
-	1		USPAT;	2003/12/22
		near10 (processor or cpu)) and (switch\$5	US-PGPUB	14:20
		or select\$5 or configurable or		
	11	reconfigurable or re-configurable) (("wirebond pad" or "wire bond pad")	USPAT;	2003/12/22
_	11	near10 (processor or cpu)) and (switch\$5	US-PGPUB	15:59
		or select\$5 or configurable or	OB PGPOB	15.55
		reconfigurable or re-configurable)		
-	954	(326/38).CCLS.	USPAT;	2003/12/22
			US-PGPUB	16:00
-	2	((326/38).CCLS.) and ("wirebond pad" or	USPAT;	2003/12/22
		"wire bond pad")	US-PGPUB	16:02
-	1058	(326/41).CCLS.	USPAT;	2003/12/22
	,	((326/41).CCLS.) and ("wirebond pad" or	US-PGPUB USPAT;	16:02 2003/12/22
-	1	"wire bond pad")	US-PGPUB	16:03
_	319	(257/e23.011).CCLS.	USPAT;	2003/12/22
		(2077 020 0227 00020	US-PGPUB	16:04
_	3	((257/e23.011).CCLS.) and ("wirebond pad"	USPAT;	2003/12/22
		or "wire bond pad")	US-PGPUB	16:06
-	65	(257/e23.032).CCLS.	USPAT;	2003/12/22
	_	//057/ 02 020) 5555	US-PGPUB	16:07
-	0	((257/e23.032).CCLS.) and ("wirebond pad"	USPAT;	2003/12/22 16:07
_	534	or "wire bond pad") (257/e23.079).CCLS.	US-PGPUB USPAT;	2003/12/22
_	334	(201/623.015).0000.	US-PGPUB	16:07
_	11	((257/e23.079).CCLS.) and ("wirebond pad"	USPAT;	2003/12/22
		or "wire bond pad")	US-PGPUB	16:11
-	401	(710/316).CCLS.	USPAT;	2003/12/22
			US-PGPUB	16:12
	0	((710/316).CCLS.) and ("wirebond pad" or	USPAT;	2003/12/22
	1.64	"wire bond pad")	US-PGPUB	16:12 2003/12/22
-	164	(710/317).CCLS.	USPAT; US-PGPUB	17:36
_	0	((710/317).CCLS.) and ("wirebond pad" or	USPAT;	2003/12/22
		"wire bond pad")	US-PGPUB	16:26
-	82	((326/38).CCLS.) and ((326/41).CCLS.) and	USPAT;	2003/12/22
		(pad and processor or microprocessor)	US-PGPUB	16:27
-	42	((326/38).CCLS.) and ((326/41).CCLS.) and	USPAT;	2003/12/22
		(pad and (processor or microprocessor))	US-PGPUB	16:27
-	35	(((326/38).CCLS.) and ((326/41).CCLS.)	USPAT;	2003/12/22 16:28
		and (pad and (processor or microprocessor))) and (configurable or	US-PGPUB	10.20
		reconfigurable or re-configurable)		
I .	l	1 - COUNTY GALANTO OF TO CONTAIN GALANTO,	<u> </u>	1

	,	1006/44		1 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2 2
-	31	((((326/38).CCLS.) and ((326/41).CCLS.)	USPAT;	2003/12/22
		and (pad and (processor or microprocessor))) and (configurable or	US-PGPUB	16:31
		reconfigurable or re-configurable)) and		
		switch\$6		
_	382	(configurable or reconfigurable or	USPAT;	2003/12/22
	302	re-configurable) near6 pin	US-PGPUB	16:50
-	70	((configurable or reconfigurable or	USPAT;	2003/12/22
		re-configurable) near6 pin) and pad and	US-PGPUB	16:50
		(processor or microprocessor) and (switch		
		or connect\$5 or select\$4)		
-	234	(configurable or reconfigurable or	USPAT;	2003/12/22
		re-configurable) near3 pin	US-PGPUB	16:50
-	34	((configurable or reconfigurable or	USPAT;	2003/12/22
		re-configurable) near3 pin) and pad and	US-PGPUB	17:33
		(processor or microprocessor) and (switch		
	2200	or connect\$5 or select\$4)	USPAT;	2003/12/22
-	2289	(257/666,676).CCLS.	US-PGPUB	17:36
	0	((257/666,676).CCLS.) and	USPAT;	2003/12/22
-		((326/38).CCLS.) and ((326/41).CCLS.) and	US-PGPUB	17:37
		((257/e23.011).CCLS.) and	05 10105	1,13,
		((257/e23.032).CCLS.) and		
		((257/e23.079).CCLS.) and		
		((710/316).CCLS.) and ((710/317).CCLS.)		
		and microcontroller		
-	142		USPAT;	2003/12/22
		((326/38).CCLS.) or ((326/41).CCLS.) or	US-PGPUB	17:38
		((257/e23.011).CCLS.) or		
		((257/e23.032).CCLS.) or		
	ļ	((257/e23.079).CCLS.) or		
		((710/316).CCLS.) or ((710/317).CCLS.))	1	1
		and microcontroller	***************************************	2002/12/22
-	71		USPAT;	2003/12/22 17:39
		((326/38).CCLS.) or ((326/41).CCLS.) or	US-PGPUB	17:39
		((257/e23.011).CCLS.) or]]
		((257/e23.032).CCLS.) or ((257/e23.079).CCLS.) or		
		((710/316).CCLS.) or ((710/317).CCLS.))		
		and microcontroller and pad		
_	57		USPAT;	2003/12/22
		((326/38).CCLS.) or ((326/41).CCLS.) or	US-PGPUB	18:09
		((257/e23.011).CCLS.) or		
		((257/e23.032).CCLS.) or		
		((257/e23.079).CCLS.) or		
1		((710/316).CCLS.) or ((710/317).CCLS.))		
1		and microcontroller and pad and		
1	_	(processor or microprocessor)	I II CDAE	2003/12/22
-	0	6509758.URPN.	USPAT	17:50
	12	 ("4642561" "4800294" "4963768"	USPAT	2003/12/22
-	12	"5107146" "5107230" "5289116"	JULIA	17:51
	1	"5473758" "5511182" "5563526"	1	
1	1	"5686844" "6057705" "6246258").PN.	1	
_	14		USPAT;	2003/12/22
	1	((326/38).CCLS.) or ((326/41).CCLS.) or	US-PGPUB	18:09
	1	((257/e23.011).CCLS.) or		
	1	((257/e23.032).CCLS.) or		
1	1	((257/e23.079).CCLS.) or		
		((710/316).CCLS.) or ((710/317).CCLS.))		
		and microcontroller and pad) not		
1		((((257/666,676).CCLS.) or		
		((326/38).CCLS.) or ((326/41).CCLS.) or		
		((257/e23.011).CCLS.) or ((257/e23.032).CCLS.) or		
		((257/e23.032).CCLS.) or	1	
		((237/e23.079).ccls.) or ((710/317).ccls.))		
		and microcontroller and pad and		
	1	(processor or microprocessor))		
_	0		USPAT	2003/12/24
				13:48

-	12	("4642561" "4800294" "4963768"	USPAT	2003/12/24
		"5107146" "5107230" "5289116"		13:48
		"5473758" "5511182" "5563526"		
		"5686844" "6057705" "6246258").PN.		
-	12	("4642561" "4800294" "4963768"	USPAT	2003/12/24
		"5107230" "5289116" "5473758"		13:49
		"5511182" "5563526" "5686844"		
		"5724009" "6057705" "6246258").PN.		
-	23	("4472647" "4698526" "4877978"	USPAT	2003/12/24
		"4896060" "4902917" "4930112"		13:50
		"4978905" "5084635" "5144167"		
		"5153450" "5157282" "5161124"		
		"5162672" "5300832" "5309044"		
		"5345112" "5353250" "5359240"		
		"5402018" "5406139" "5600267"		
		"5732027" "6047352").PN.		
_	12	("4642561" "4800294" "4963768"	USPAT	2003/12/30
		"5107146" "5107230" "5289116"		13:41
-	1	"5473758" "5511182" "5563526"		
		"5686844" "6057705" "6246258").PN.		
_	0	6509758.URPN.	USPAT	2003/12/30
				14:17
_	12	("4642561" "4800294" "4963768"	USPAT	2003/12/30
		"5107230" "5289116" "5473758"		14:17
		"5511182" "5563526" "5686844"		
		"5724009" "6057705" "6246258").PN.		
_	3	("5757207" "5768598" "5883526").PN.	USPAT	2003/12/30
		, , , , , , , , , , , , , , , , , , , ,		17:28
-	l o '	6188241.URPN.	USPAT	2003/12/30
ļ				17:29
_	6	("5701517" "5715197" "5737764"	USPAT	2003/12/30
		"5748982" "5822610" "5835965").PN.		17:29
_	27	"analog circuit" and "digital circuit"	USPAT;	2003/12/30
		and switch and pad and processor and	US-PGPUB	17:52
		(microcontroller or "micro controller" or		
		micro-controller)		
_	0	20020108006.URPN.	USPAT	2003/12/30
				17:50
-	0	"analog circuit" and "digital circuit"	EPO; JPO;	2003/12/30
		and switch and pad and processor and	DERWENT;	17:52
		(microcontroller or "micro controller" or	IBM TDB	ľ
		micro-controller)	_	
-	36	"analog circuit" and "digital circuit"	USPAT;	2003/12/30
		and switch and pad and (processor or	US-PGPUB	17:53
		microprocessor or cpu) and		
		(microcontroller or "micro controller" or		
		micro-controller)	ŀ	
-	0	6192431.pn. and (analog or digital)	USPAT;	2004/01/09
			US-PGPUB	12:04
-	1	6192431.pn.	USPAT;	2004/01/09
		_	US-PGPUB	13:09
-	883353	(gate or counter or latch\$3 or decoder or	USPAT;	2004/01/09
		encoder or register or flip-flop or "flip	US-PGPUB;	13:14
		flop" or timer) and (filter or amplifier	EPO; JPO;	
		or switch or clipper or limiter or summer	DERWENT;	
		or buffer)	IBM TDB	
-	19576	((gate or counter or latch\$3 or decoder	USPAT;	2004/01/09
		or encoder or register or flip-flop or	US-PGPUB;	13:15
		"flip flop" or timer) and (filter or	EPO; JPO;	
		amplifier or switch or clipper or limiter	DERWENT;	
		or summer or buffer)) and microcontroller	IBM_TDB	
-	3286	(((gate or counter or latch\$3 or decoder	USPAT;	2004/01/09
		or encoder or register or flip-flop or	US-PGPUB;	13:15
		"flip flop" or timer) and (filter or	EPO; JPO;	
		amplifier or switch or clipper or limiter	DERWENT;	
		or summer or buffer)) and	IBM_TDB	
		microcontroller) and pad	L	

_	2929	((((gate or counter or latch\$3 or decoder	USPAT;	2004/01/09
		or encoder or register or flip-flop or	US-PGPUB;	13:16
	}	"flip flop" or timer) and (filter or	EPO; JPO;	
		amplifier or switch or clipper or limiter	DERWENT;	
		or summer or buffer)) and	IBM TDB	
	İ	microcontroller) and pad) and (processor	_	
		or microprocessor)		
_	2581	(((((gate or counter or latch\$3 or	USPAT;	2004/01/09
	1	decoder or encoder or register or	US-PGPUB;	13:16
		flip-flop or "flip flop" or timer) and	EPO; JPO;	
		(filter or amplifier or switch or clipper	DERWENT;	
		or limiter or summer or buffer)) and	IBM TDB	
		microcontroller) and pad) and (processor	_	
		or microprocessor)) and switch\$4		į l
_	l 0	(((((gate or counter or latch\$3 or	USPAT;	2004/01/09
		decoder or encoder or register or	US-PGPUB;	13:17
		flip-flop or "flip flop" or timer) and	EPO; JPO;	
		(filter or amplifier or switch or clipper	DERWENT;	
		or limiter or summer or buffer)) and	IBM TDB	
		microcontroller) and pad) and (processor	-	
		or microprocessor)) and switch\$4) and		
		("selectively connects" near10 pad)		
_	1325	((((((gate or counter or latch\$3 or	USPAT;	2004/01/09
	1000	decoder or encoder or register or	US-PGPUB;	13:18
		flip-flop or "flip flop" or timer) and	EPO; JPO;	: - :
		(filter or amplifier or switch or clipper	DERWENT;	
		or limiter or summer or buffer)) and	IBM TDB	
	1	microcontroller) and pad) and (processor		
		or microprocessor)) and switch\$4) and		
		selectively		
_	27		USPAT;	2004/01/09
	[decoder or encoder or register or	US-PGPUB;	13:18
		flip-flop or "flip flop" or timer) and	EPO; JPO;	
		(filter or amplifier or switch or clipper	DERWENT;	
		or limiter or summer or buffer)) and	IBM TDB	
		microcontroller) and pad) and (processor	1211_122	
		or microprocessor)) and switch\$4) and		1
		"selectively connects"		
1		serectively connects		

-
**

·
- i
- ·
- ·
. ,
. ,
. ,
. ,
. ,
. ,
. ,
. ,
. ,
. ,
. ,
. ,
. ,
. ,
. ,
. ,
. ,
-
_
-
-
-
-
Finition Modules and migh Density Packaging, 1998, Proceedings, 1998 / III
ליים איים איים איים איים איים איים איים
1 Multichia Madules and High Density Packaging 1998 Droceedings 1998 7th
Multichin Madulae and High Dancity Darkaning 1008 Droceedings 1008 7th
Andread to the desired and think Demarks Dealer and Account and the second seco
(כומוכז, ווירי זוי, רומכוי, רוזי, במיימוסז, רובי, בכוונטווכוו, טיזי, רככ, טיוי,
I CHAMES, H.K. JC.: Mach. K.J.: Edwards, K.J.: Lentonen, S.J.: Lee, D.W.:
I LANTIBO TIK IT : MACO K I . TONIATOO K I . I POTODOO S I . I DO I I M .
_
1
\ -
^
^
^
2
2
, c
7
[Ab
TAP (
[Ab
Tab (
[Ab
[Ab]
[Ab
Pag [Ab
Pag [Ab
Pag [Ab
Page(s): 897 -904 [Abstract] [PDF Full-Text (787 KB)] IEEE CNF > Wirehonding: reinventing the process for MCMs
Pag
May Pag
Pag [Ab
Elec Ma) Pag
Flecton May
ove Tay Elec May Pag
Ove Tay Tay Bec May Pag
30
ove Tay Elec May Pag
1 1 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0 0
,,,
,,,

[Abstract] [PDF Full-Text (212 KB)] IEEE CNF

ch O e eee e ch eee

ch ch

ch h

e)

ge

3 A new approach to the robust wirebonding

Cuong Van Pham; Huth, K.;

Advanced Packaging Materials: Processes, Properties and Interfaces, 2001.

Proceedings. International Symposium on, 11-14 March 2001

Page(s): 379 -385

[PDF Full-Text (852 KB)] IEEE CNF [Abstract]

4 The effect of wirebond geometry and die setting on wire sweep

Tay, A.A.O.; Yeo, K.S.; Wu, J.H.;

Components, Packaging, and Manufacturing Technology, Part B: Advanced Packaging, IEEE Transactions on [see also Components, Hybrids, and Manufacturing Technology, IEEE Transactions on], Volume: 18 Issue: 1, Feb. 1995

Page(s): 201 -209

[PDF Full-Text (668 KB)] IEEE JNL [Abstract]

5 Analysis and application of vibration behaviour for wirebonding capillary

by transmission laser vibrometer

Tamura, Y.; Miyahara, Y.; Suzuki, H.;

Electronics Manufacturing Technology Symposium, 1998. Twenty-Third IEEE/CPMT,

19-21 Oct. 1998

Page(s): 72 -75

[PDF Full-Text (450 KB)] IEEE CNF [Abstract]

Charles, H.K., Jr.; Mach, K.J.; Lehtonen, S.J.; Francomacaro, A.S.; DeBoy, J.S.; 6 High-frequency wirebonding: process and reliability implications

Edwards, R.L.;

Electronic Components and Technology Conference, 2002. Proceedings. 52nd, 28-31

당 당 b ರೂ eee ch eee

ch h (J geo o O ပ

ch ch

May 2002

Page(s): 881 -890

[Abstract] [PDF Full-Text (1140 KB)] IEEE CNF

7 Wirebond reliability in IGBT-power modules: application of high resolution strain and temperature mapping

Mehrotra, V.; Jun He; Dadkhah, M.S.; Rugg, K.; Shaw, M.C.;

Power Semiconductor Devices and ICs, 1999. ISPSD '99. Proceedings., The 11th

International Symposium on , 26-28 May 1999

Page(s): 113 -116

[Abstract] [PDF Full-Text (380 KB)] IEEE CNF

8 Wirebonding Reliability Techniques and Analysis

Ebel, G.; Jeffery, J.; Farrell, J.;

Components, Hybrids, and Manufacturing Technology, IEEE Transactions on [see also IEEE Trans. on Components, Packaging, and Manufacturing Technology, Part A, B,

C], Volume: 5 Issue: 4, Dec 1982

Page(s): 441 -445

[Abstract] [PDF Full-Text (1024 KB)] IEEE JNL

9 DC to 100 GHz chip-to-chip interconnects with reduced tolerance

sensitivity by adaptive wirebonding

Goebel, U.;

Electrical Performance of Electronic packaging, 1994., IEEE 3rd Topical Meeting on, 2-

4 Nov. 1994

Page(s): 182 -185

e ch eee g e ch

e e ch e ch ge

ch h

b

[PDF Full-Text (276 KB)] IEEE CNF [Abstract]

10 The effect of fillet height and bondline thickness on the mechanical performance of a plastic package

Rasiah, I.J.; Breach, C.;

Electronic Materials and Packaging, 2000. (EMAP 2000). International Symposium on ,

30 Nov.-2 Dec. 2000

Page(s): 416 -420

[PDF Full-Text (368 KB)] IEEE CNF [Abstract]

11 Analysis of wirebonding techniques for contacting high concentrator solar cels

Rey-Stolle, I.; Algora, C.; Advanced Packaging, IEEE Transactions on [see also Components, Packaging and Manufacturing Technology, Part B: Advanced Packaging, IEEE Transactions on], Volume: 26 Issue: 1, Feb. 2003

Page(s): 47 -53

[PDF Full-Text (357 KB)] IEEE JNL [Abstract]

12 A three-dimensional modeling of wire sweep incorporating resin cure

Wu, J.H.; Tay, A.A.O.; Yeo, K.S.; Lim, T.-B.;

Components, Packaging, and Manufacturing Technology, Part B: Advanced Packaging, IEEE Transactions on [see also Components, Hybrids, and Manufacturing Technology, EEE Transactions on], Volume: 21 Issue: 1, Feb. 1998

Page(s): 65 -72

[Abstract] [PDF Full-Text (208 KB)] IEEE JNL

13 Integrated Taguchi method and neural network analysis f physical

ch ð 50 e eee ch eee

ch h o ge 년 당 당

profiling in the wirebonding process

Yu-Lung Lo; Tsao, C.C.;

Components and Packaging Technologies, IEEE Transactions on [see also Components, Packaging and Manufacturing Technology, Part A: Packaging Technologies, IEEE Transactions on], Volume: 25 Issue: 2, June 2002

Page(s): 270 -277

[Abstract] [PDF Full-Text (329 KB)] IEEE JNL

14 Convection modelling of flip chip and wirebond surface mounted modules

Yuan. T.D.:

Thermal Phenomena in Electronic Systems, 1996. I-THERM V., Inter-Society

Conference on , 29 May-1 June 1996

Page(s): 174 -179

[Abstract] [PDF Full-Text (432 KB)] IEEE CNF

15 70 µm fine pitch wirebonding

Nguyen, L.; Singh, I.; Murray, C.; Jackson, J.; DeRosa, J.; Ho, D.;

Electronics Manufacturing Technology Symposium, 1998. Twenty-Third IEEE/CPMT,

19-21 Oct. 1998

Page(s): 394 -400

[Abstract] [PDF Full-Text (1271 KB)] IEEE CNF

1 2 3 4 5 6 7 8 9 10 [Next]

Join IEEE | Web Account | New this week | OPAC Linking Information | Your Feedback | Technical Support | Email Alerting No Robots Please | Release Notes | IEEE Online Publications | Help | FAQ | Terms | Back to Top Home | Log_out | Journals | Conference Proceedings | Standards | Search by Author | Basic Search | Advanced Search

Copyright © 2003 IEEE — All rights reserved